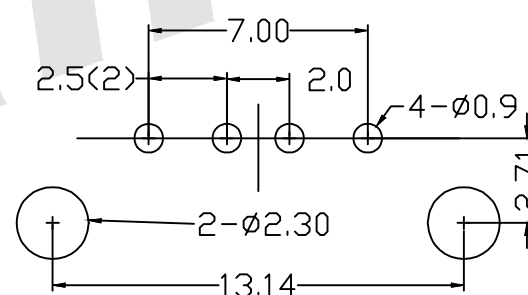
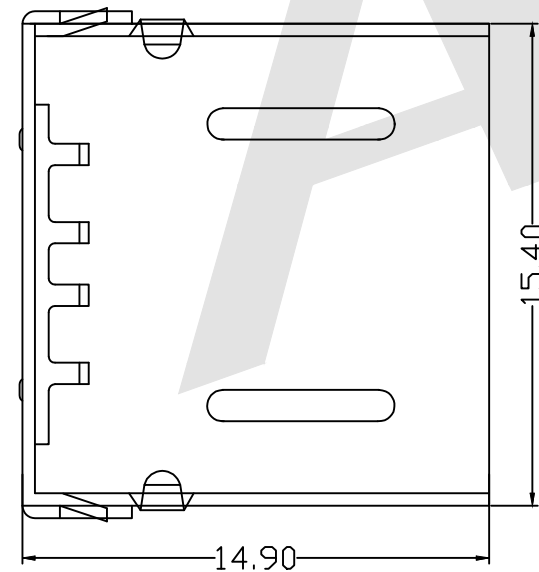
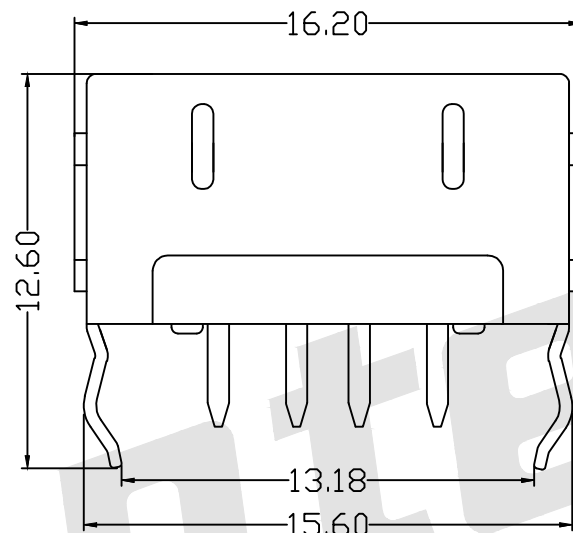
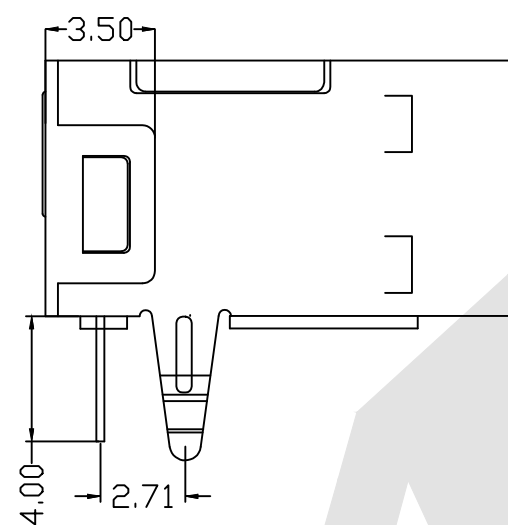


HSF



PCB LAYOUT

Specifications:
 Current Rating: 1.5A Max
 Contact Resistance: 30 milliohms MAX
 Dielectric Withstanding Voltage:
 500V AC AT Sea Level
 Insulation Resistance: 1000 Megohms MIN
 Housing:
 Temperature Thermoplastics, PBT UL 94V-0
 Contact:
 Copper Alloy T=0.25mm Plated Gold in Mating Area;
 Tin On Solder Tails
 Shell: Iron T=0.30mm Nickel/Plating
 Ordering Code:

UAFR13 - X - X - X - X - X - X
 ① ② ③ ④ ⑤ ⑥ ⑦

- ① Series No:
- ② Shell Material:
B:Brass
I:Iron
S:stainless steel
- ③ Insulator Material:
P:PBT+30%GF
L:LCP
- ④ Contact Material:
B:Brass
P:phosphor copper
- ⑤ Contact Plating:
G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold
- ⑥ Color Insulator:
A:White
B:Black
- ⑦ Packing:
A:Tray
B:Bag
C:Tube
D:Tape & Reel

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
 DRAW Lv Xun Hua DATE 17/06/2019
 CHECK BobYang DATE 17/06/2019



Antenk® ANTENK ELECTRONICS CO., LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE:
 USB A Type Receptacle Angle DIP13.14mm, Full shield

DRAWING NO: UAFR13-XXXXXX
 PRODUCT NO: UAFR13-XXXXXX

REV	DESCRIPTION	DATE